

U.S. Patent Application Serial No. 09/817,366
Response dated August 25, 2004
Reply to OA of February 25, 2004

AMENDMENT TO THE DRAWINGS:

The attached sheets of drawings include formal Figs. 1(a), 1(b), 1(c), 1(d), 2(a), 2(b), 2(c), 2(d), 3(a), 3(b), 3(c), 4-6, 7(a), 7(b), 8(a), 8(b), 9, 10(a), 10(b), 10(c), 11(a), 11(b), 12-14, 15(a), 15(b), 15(c), 16(a), 16(b), 16(c), 17(a), 17(b), 18 and 19. These sheets of formal drawings replace the original sheets including Figs. 1(a), 1(b), 1(c), 1(d), 2(a), 2(b), 2(c), 2(d), 3(a), 3(b), 3(c), 4-6, 7(a), 7(b), 8(a), 8(b), 9, 10(a), 10(b), 10(c), 11(a), 11(b), 12-14, 15(a), 15(b), 15(c), 16(a), 16(b), 16(c), 17(a), 17(b), 18 and 19, respectively.

[illegible]



FIG.2(a)

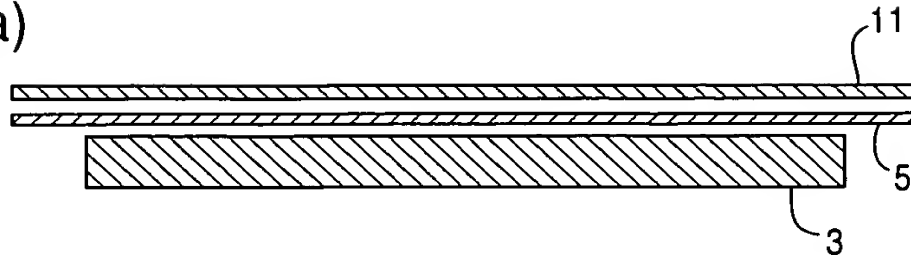


FIG.2(b)

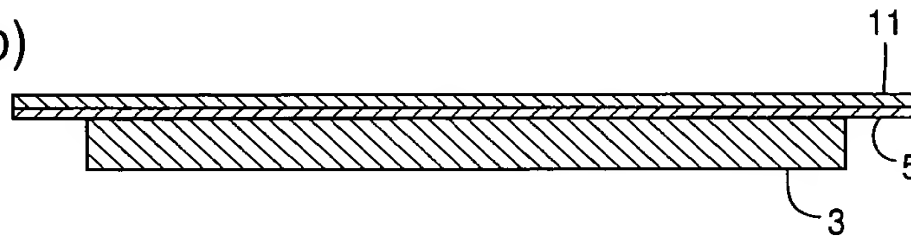


FIG.2(c)

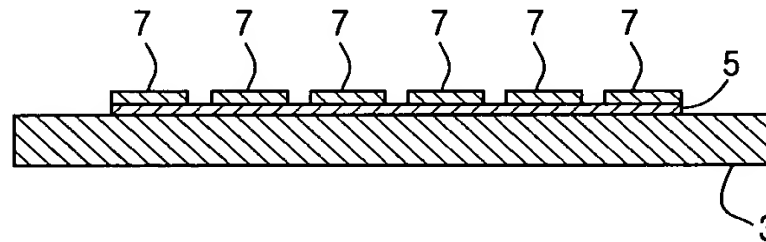


FIG.2(d)

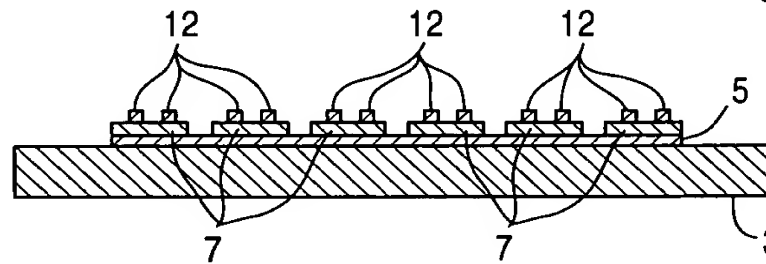




FIG.3(a)

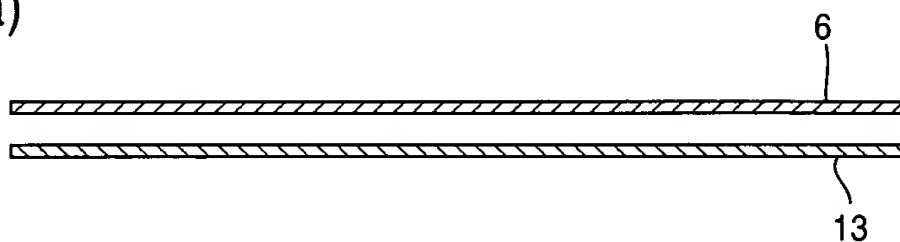


FIG.3(b)

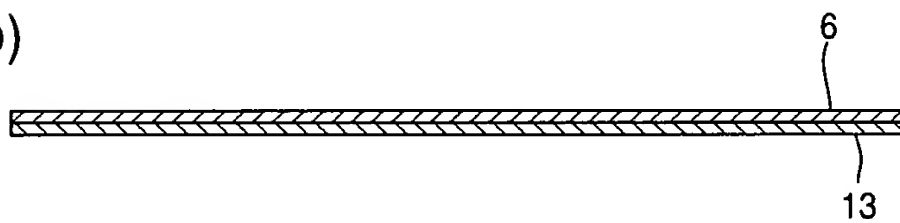


FIG.3(c)

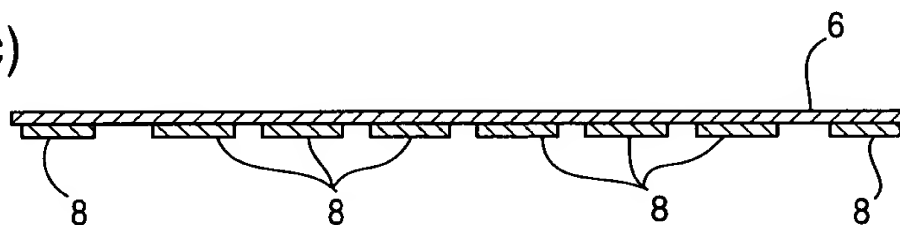




FIG.4

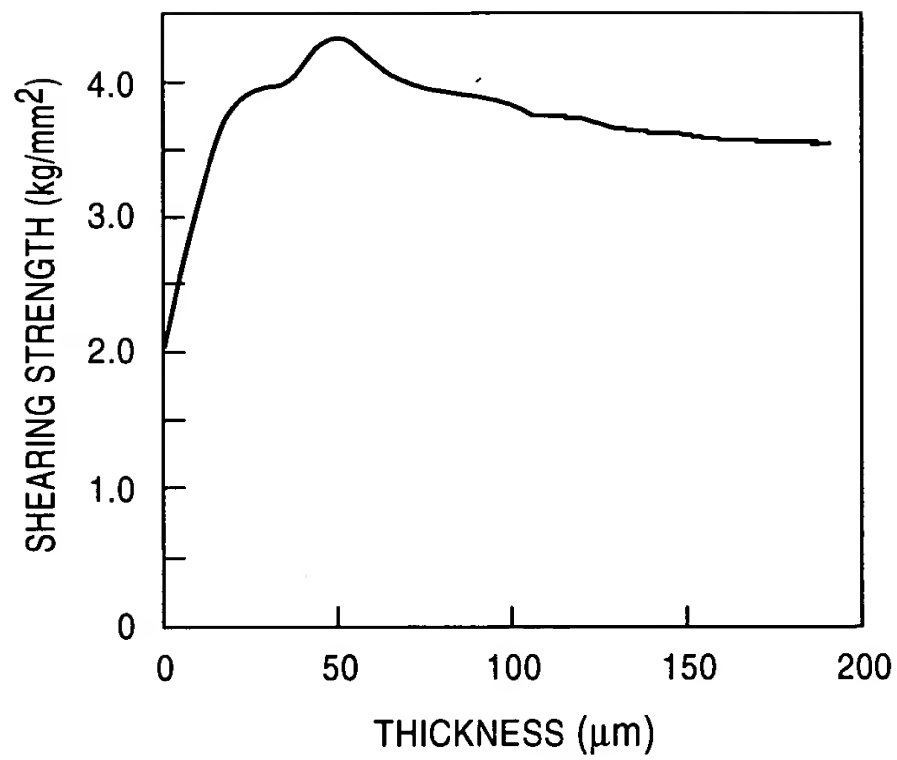




FIG.5

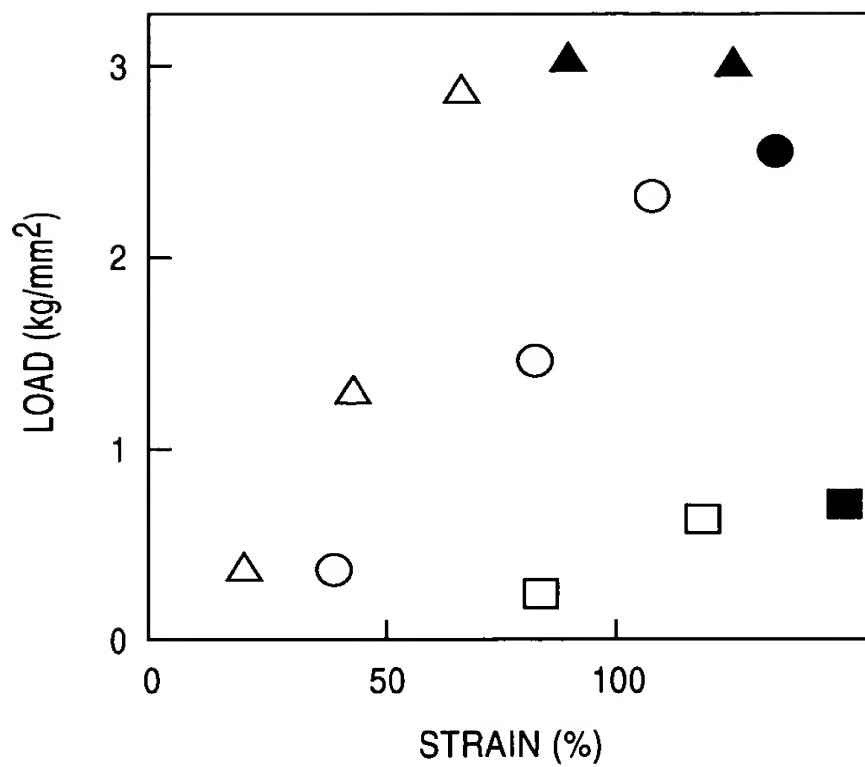




FIG.6

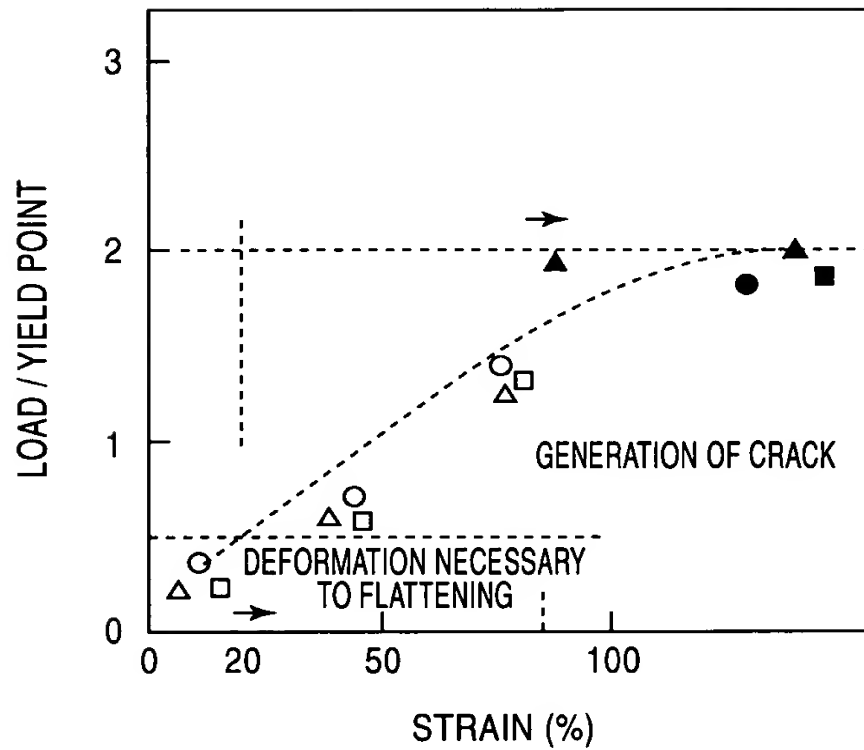




FIG.7(a)

(HIGH PRESSURE DURING SOFT SOLDERING, WITHOUT COPPER POWER)

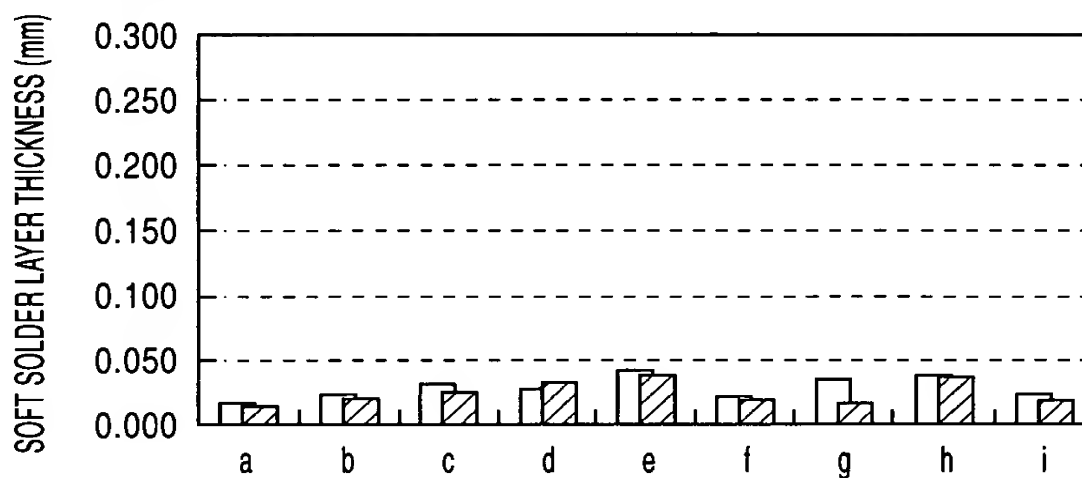


FIG.7(b)

(HIGH PRESSURE DURING SOFT SOLDERING, WITH COPPER POWER)

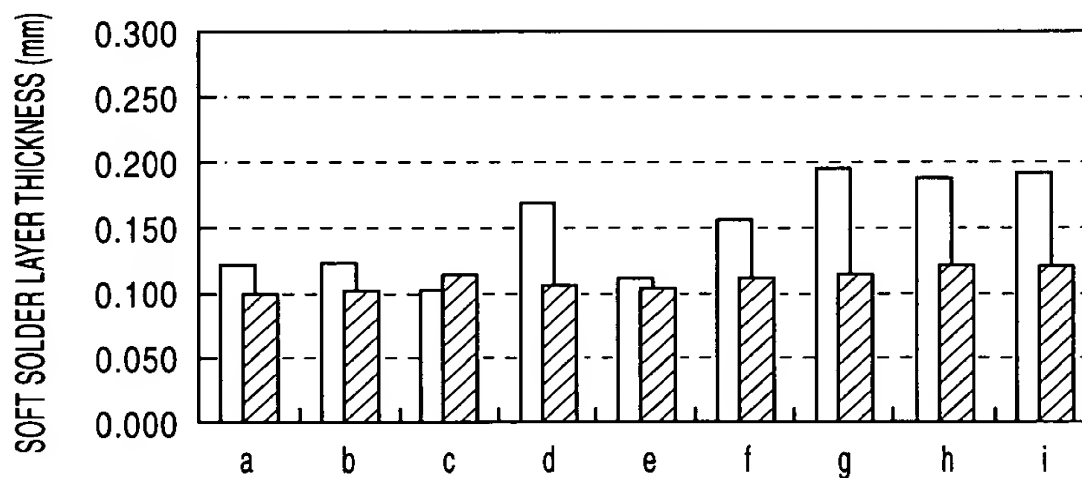




FIG.8(a)

(LOW PRESSURE DURING SOFT SOLDERING, WITHOUT COPPER POWER)

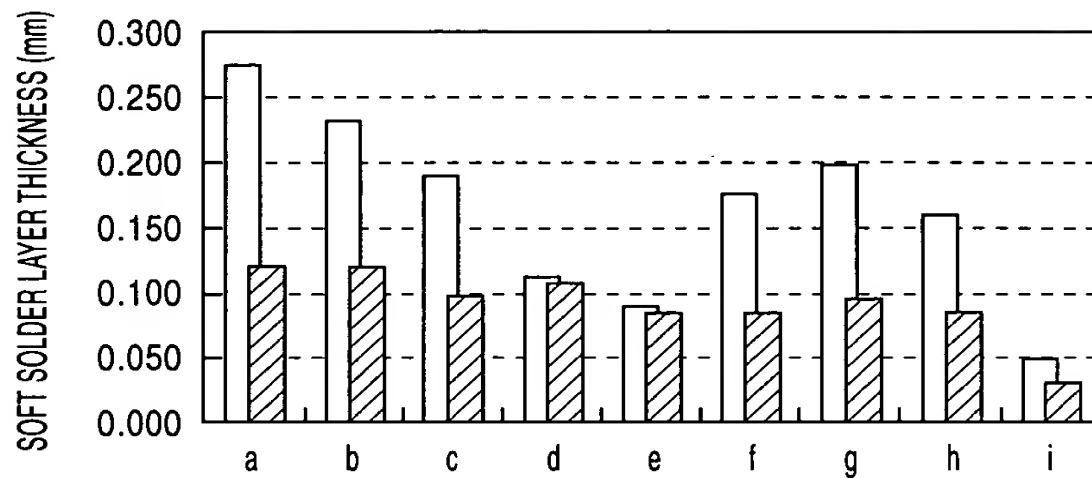


FIG.8(b)

(LOW PRESSURE DURING SOFT SOLDERING, WITH COPPER POWER)

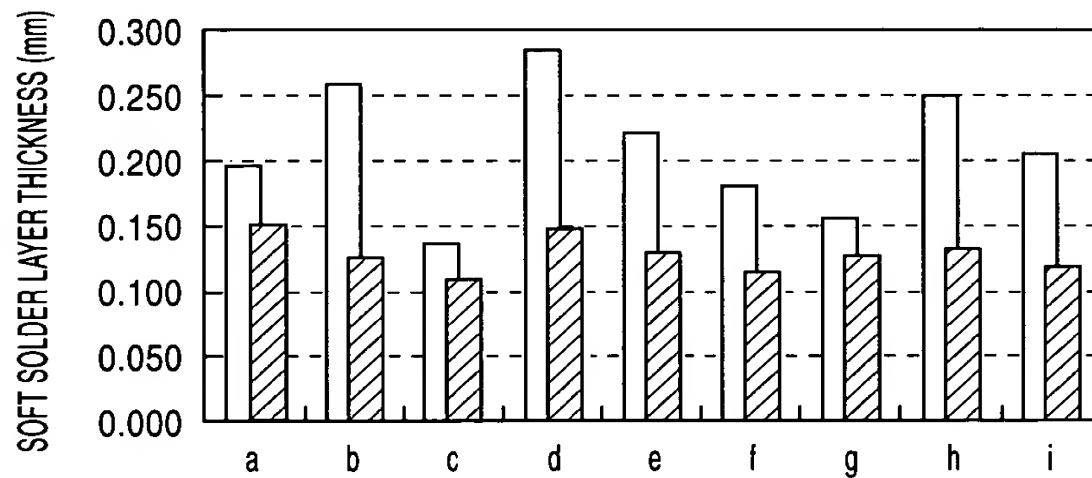




FIG.9

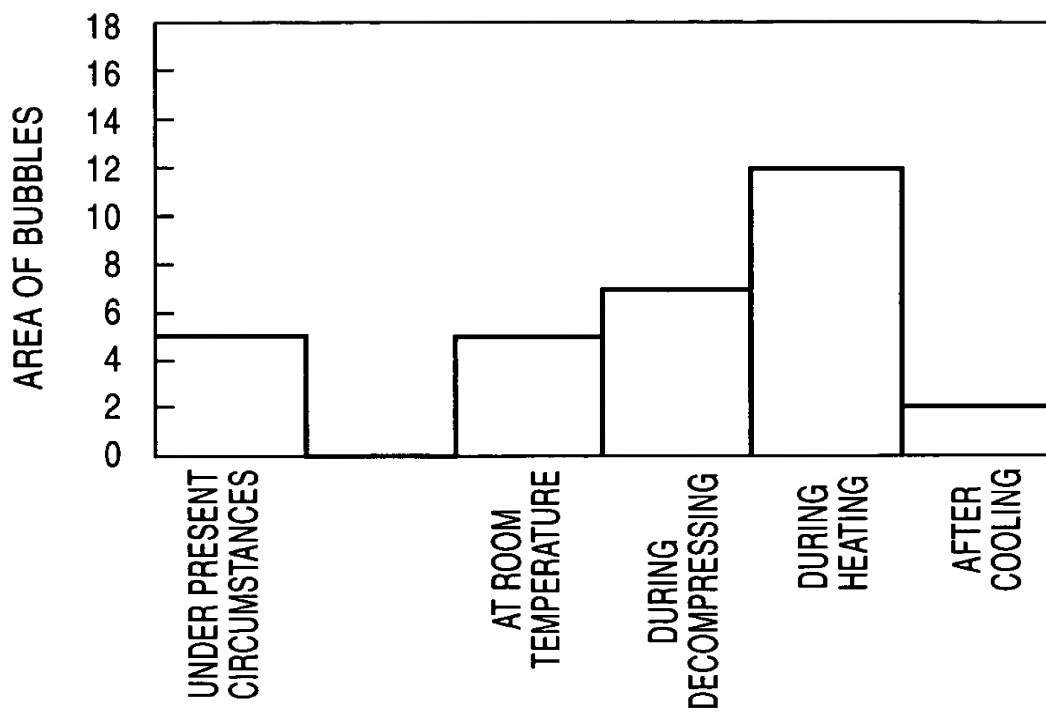




FIG. 10(a)
IDEAL

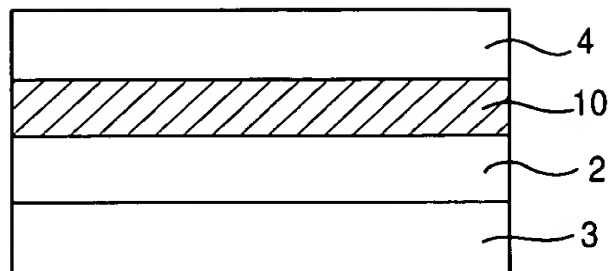


FIG. 10(b)
UNDER PRESENT
CIRCUMSTANCES

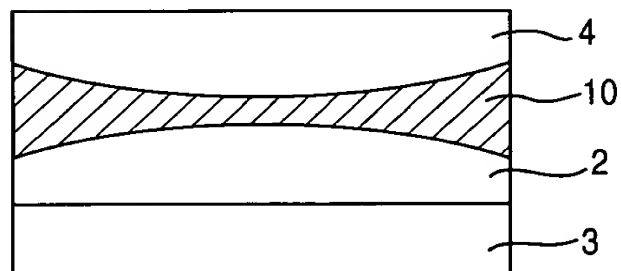


FIG. 10(c)
PRESENT INVENTION

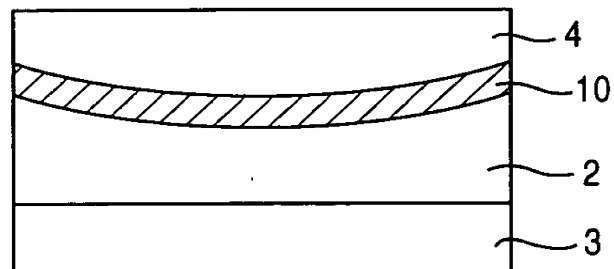




FIG.11(a)
PRESENT INVENTION

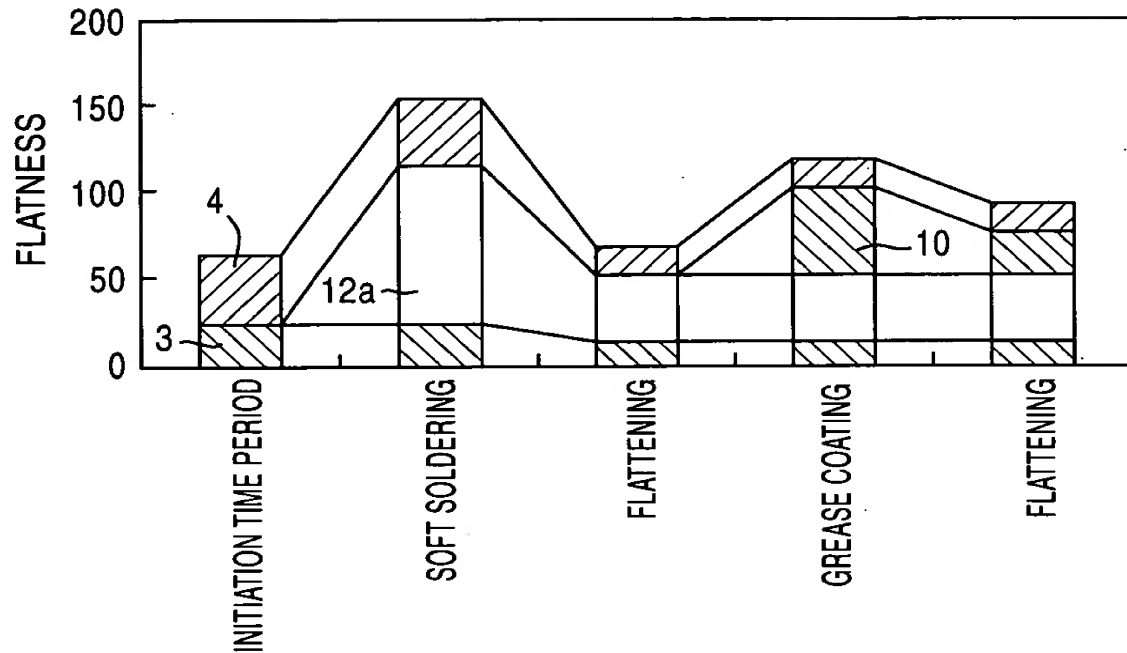


FIG.11(b)
UNDER PRESENT CIRCUMSTANCES

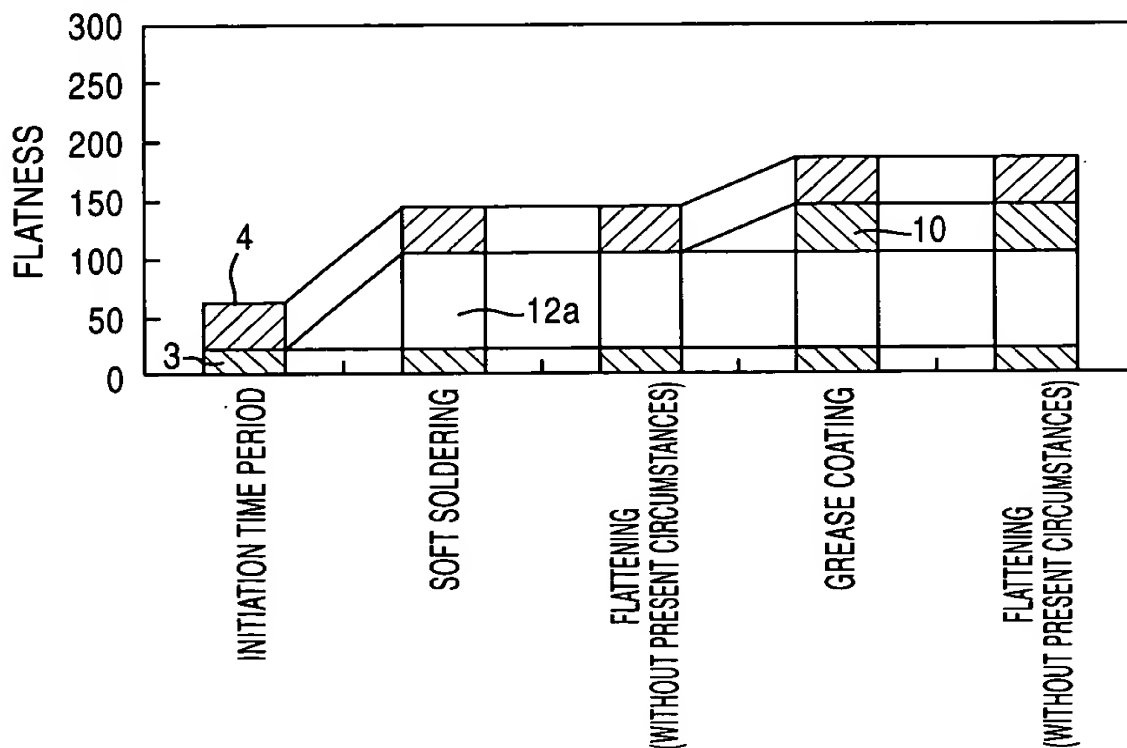




FIG.12

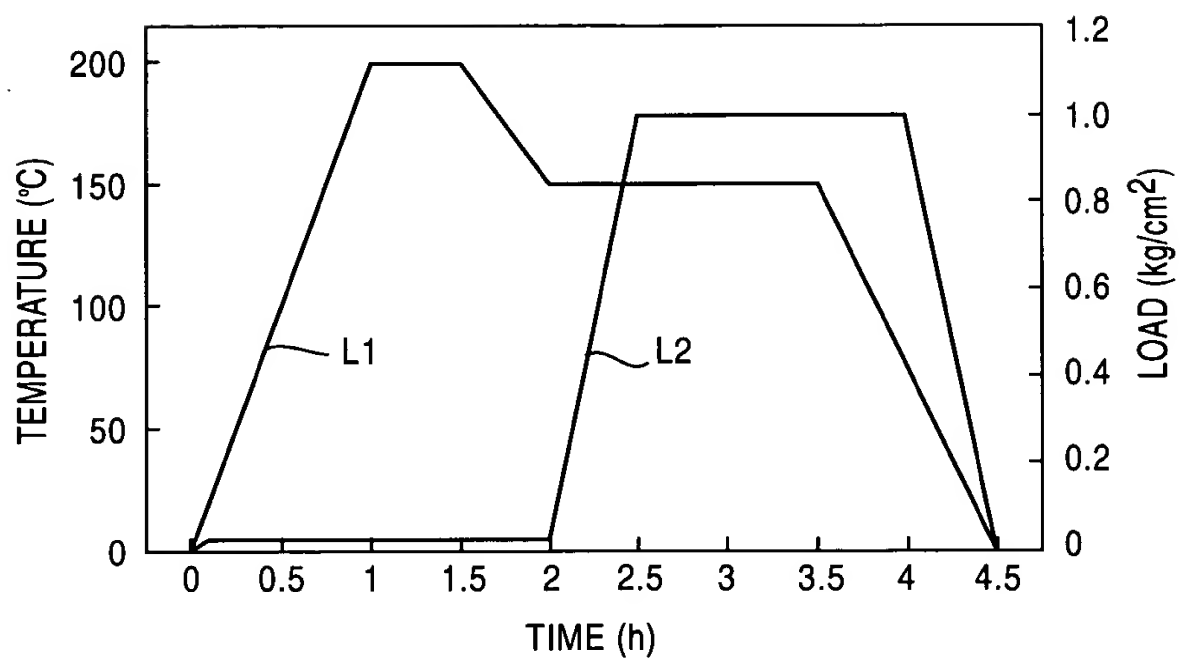




FIG.13

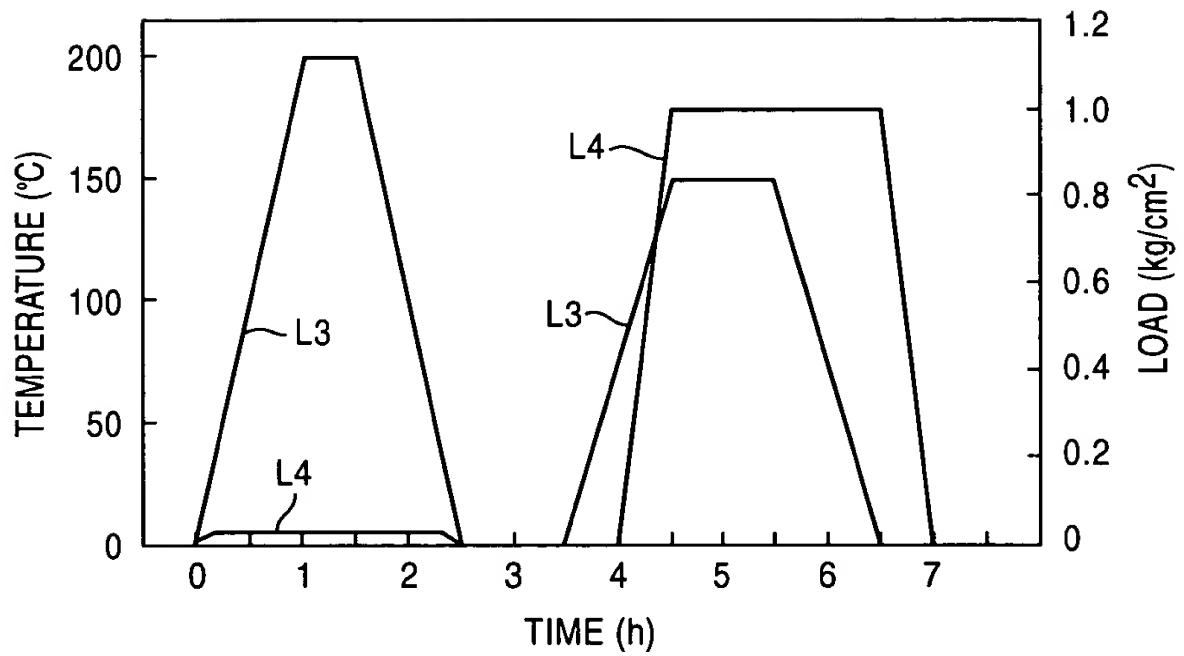
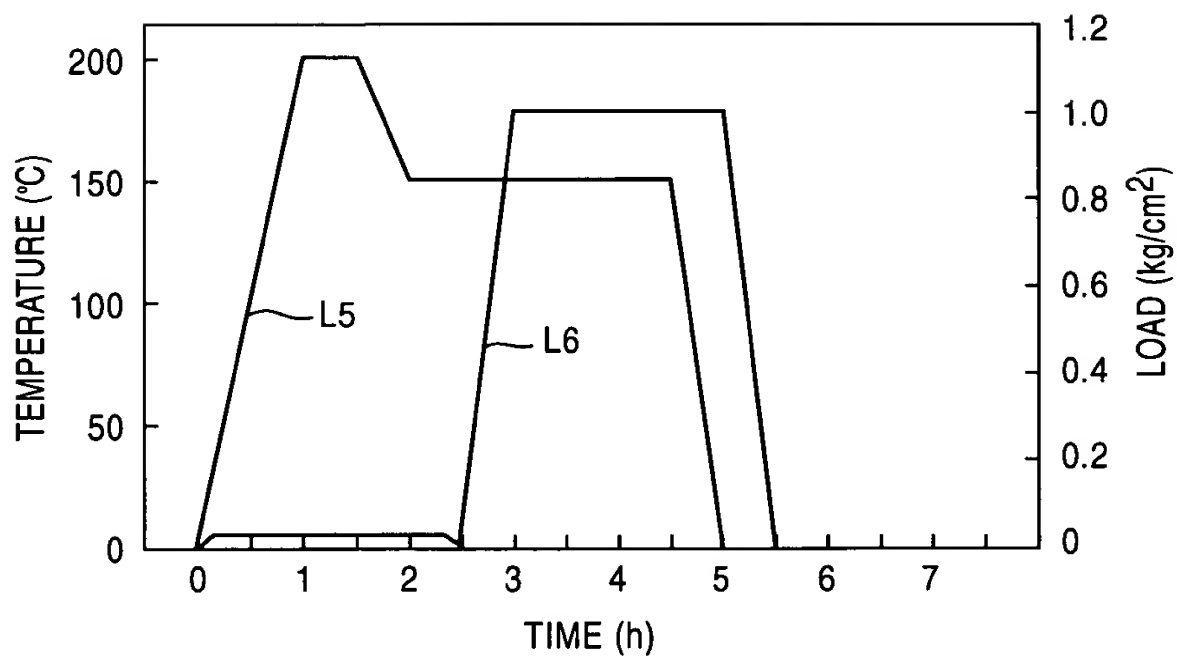




FIG.14



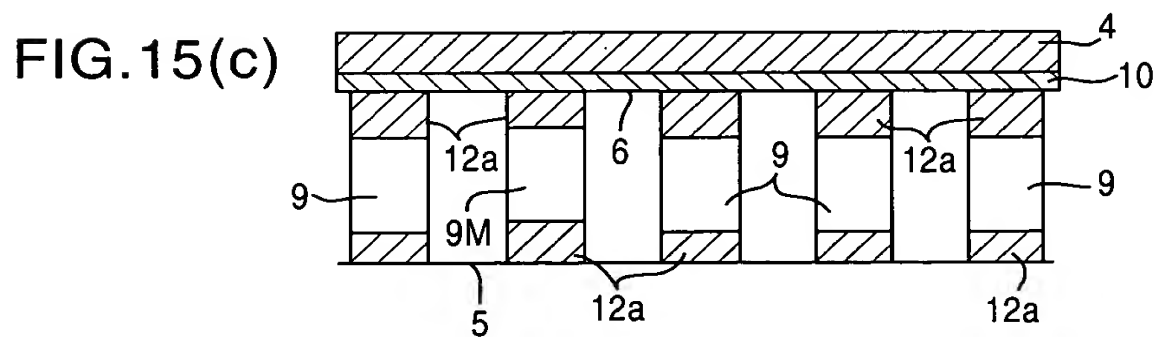
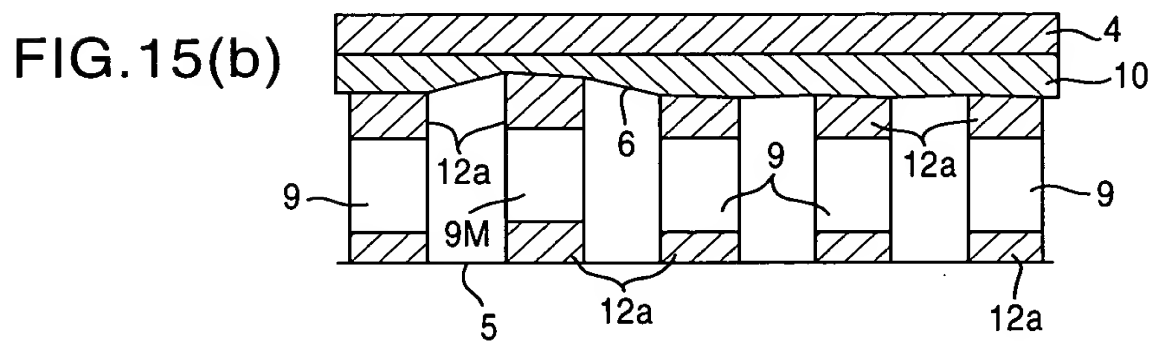
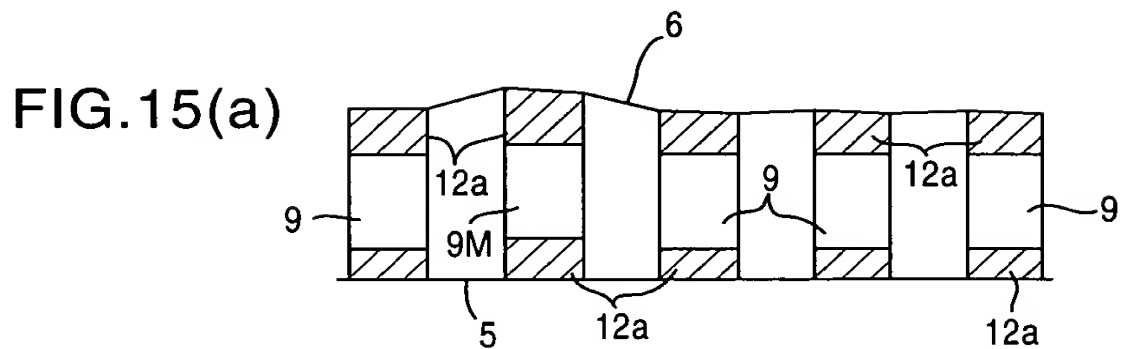




FIG.16(a)

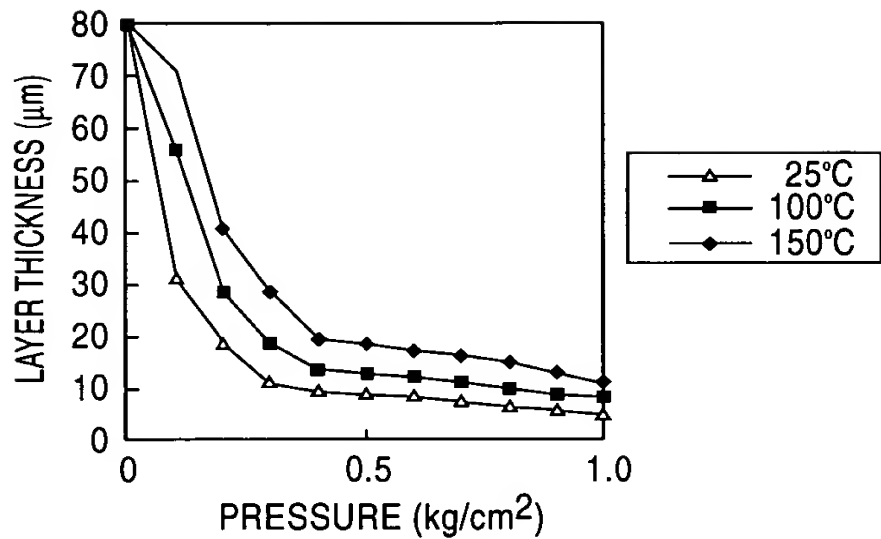


FIG.16(b)

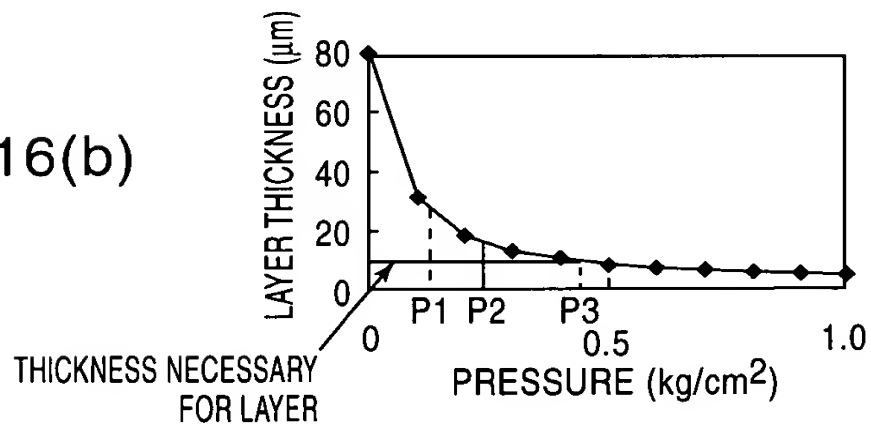
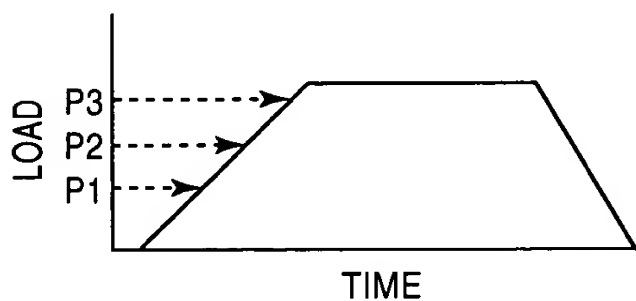


FIG.16(c)



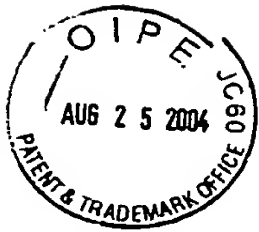


FIG.17(a)

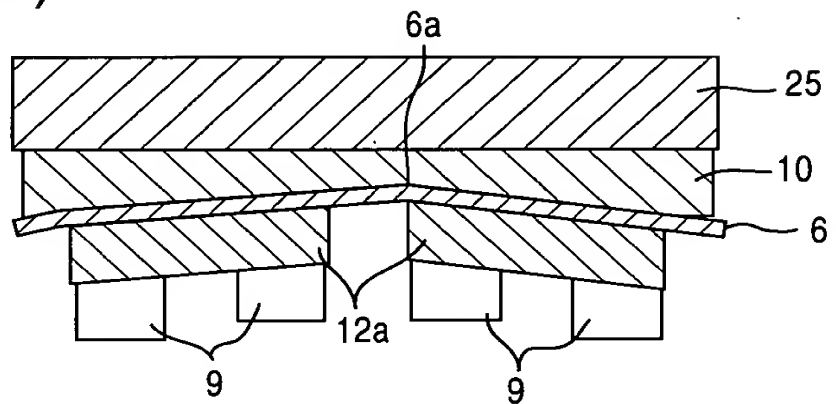


FIG.17(b)

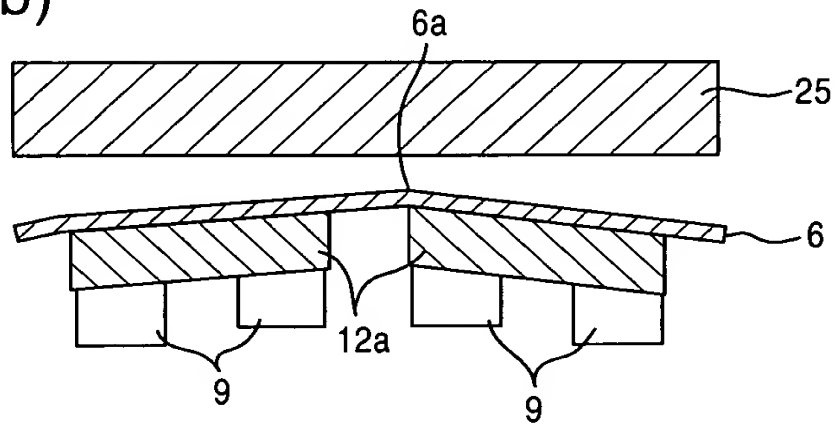




FIG.18

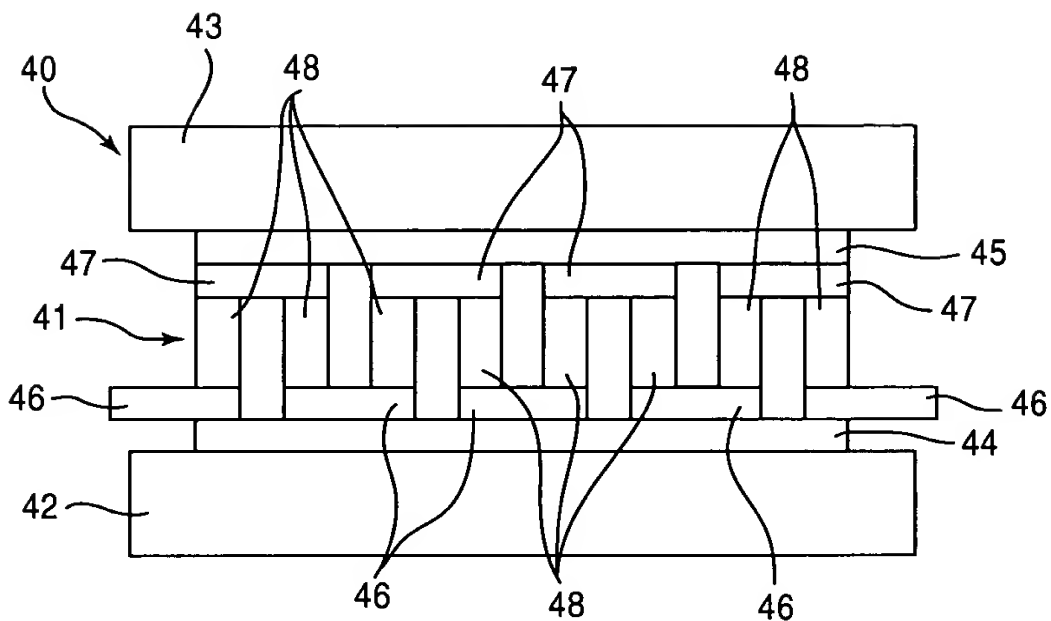




FIG.19
PRIOR ART

